

PCN #20250303002.1

**Qualification of TI Chengdu as an additional assembly site for select devices
Change Notification / Sample Request**

Date: March 03, 2025

To: Mouser PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250303002.1**Attachment: 1****Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS562206DRLR	NULL
TPS563203DRLR	NULL
TPS563206DRLR	NULL
TPS562203DRLR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN#20250303002.1	PCN Date:	March 03, 2025
Title:	Qualification of TI Chengdu as an additional assembly site for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	June 01, 2025	Sample requests accepted until:	May 02, 2025*
*Sample requests received after May 02, 2025 will not be supported.			
Change Type:			
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/>	Wafer Fab Material
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/>	Wafer Fab Process
PCN Details			
Description of Change:			
Texas Instruments Incorporated is announcing the qualification of TI Chengdu (CDAT) as an alternate Assemblysite for the list of devices below. There are no construction differences between PHI and CDAT built devices.			
Reason for Change:			
Supply continuity			
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):			
None			
Impact on Environmental Ratings			
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.			
RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change
Changes to product identification resulting from this PCN:			
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
PHI	PHI	PHL	Baguio City
TI Chengdu	CDAT	CHN	Chengdu
Sample product shipping label (not actual product label)			
 MADE IN: Malaysia 2DC: 2Q: MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: LBL: 5A (L)T0:1750	 	(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY(1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CS0:SHE (21L) CCO:USA (22L) AS0:MLA (23L) AC0:MYS	
Product Affected:			
TPS562203DRLR	TPS562206DRLR	TPS563203DRLR	TPS563206DRLR

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS563203DRLR	QBS Reference: TPS562231DRLR	QBS Reference: TPS563249DDCR	QBS Reference: TPS5139RJER	QBS Reference: TPS563203DRLR	QBS Reference: TPS563202DRLR	QBS Reference: TPS563203DRLR	QBS Reference: TPS62A02DRLR
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	-	3/231/0	-	-	-	-
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	1/77/0	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	-	-	-	3/231/0	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	3/231/0	3/231/0	-	1/77/0	-	-	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	1/77/0	-	-	3/231/0	3/231/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	-	-	3/231/0	-	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	1/77/0	-	-	-	1/77/0	-	-	1/77/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	3/231/0	3/231/0	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	3/231/0	1/77/0	1/77/0	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0	-	-	-	-

Type	#	Test Name	Condition	Duration	Qual Device: TPS563203DRLR	QBS Reference: TPS562231DRLR	QBS Reference: TPS563249DDCR	QBS Reference: TPS5139RJER	QBS Reference: TPS563203DRLR	QBS Reference: TPS563202DRLR	QBS Reference: TPS563203DRLR	QBS Reference: TPS62A02DRLR
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder.	-	-	3/66/0	3/66/0	-	-	1/22/0	-	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	3/15/0	-	1/5/0	-	-	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	-	-	1/3/0	-	1/3/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	1/3/0	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	1/3/0	-	1/3/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	3/90/0	1/30/0	-	-	-
FTY	E6	Final Test Yield	-	-	1/1/0	-	-	3/3/0	1/1/0	-	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device [TPS563203DRLR](#) is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

 Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2405-026

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.